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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2835
Examiner: M. Datskovskiy

In Re PATENT APPLICATION OF:

Applicant: Seiji ANDOH)

Serial No.: 09/376,063)

Filed: August 17, 1999)

For: PACKAGE STRUCTURE FOR A)
SEMICONDUCTOR DEVICE)

Attorney Ref: OKI 226)

AMENDMENT

May 13, 2002

Commissioner for Patents
Washington, D.C. 20231
Box – Non-Final Office Action

Sir:

This Amendment is filed in response to the Office Action dated December 13, 2001, the time for response to which is extended up to and including May 13, 2002, by the Petition for Extension of Time submitted here with. Please amend the above-referenced application as follows:

IN THE SPECIFICATION:

Please replace the paragraph on page 4, lines 20-26, with the following:

As shown in Fig. 2, the radiation solder bumps 13 are located in the central region of the back surface of the substrate 11a. Surrounding

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